Notes: (Unless Otherwise Specified).
1) ALL DIMENSIONS ARE IN MM.
2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3) BALL DIAMETER (BEFORE REFLOW): 0.63mm (25 MIL).
4) SOLDER MASK DEFINED PAD OPENING: 0.45mm (17.7 MIL).
5) PAD Cu DIAMETER: 0.60mm (23.6 MIL).
6) SUBSTRATE MATERIAL: BT.
7) DUMMY DIE IS OPTIONAL.
8) DAISY CHAIN PATTERN (SEE PAGE 2).
9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

**PART NUMBER TABLE**

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>BALL ALLOY</th>
<th>Pb-Free</th>
<th>RoHS</th>
<th>Si DIE</th>
</tr>
</thead>
<tbody>
<tr>
<td>BGA416T1.0C-DC262BD</td>
<td>Sn96.5/Ag3.0/Cu0.5</td>
<td>YES</td>
<td>YES</td>
<td>YES</td>
</tr>
<tr>
<td>BGA416T1.0-DC262BD</td>
<td>Sn63/Pb37</td>
<td>NO</td>
<td>NO</td>
<td>YES</td>
</tr>
</tbody>
</table>
Notes:
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
   DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER: 0.60mm (23.6 MIL).
3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.15mm (6 MIL).
4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.45mm (17.7 MIL).